

MA2Z030 Series (MA30 Series)

Silicon epitaxial planar type

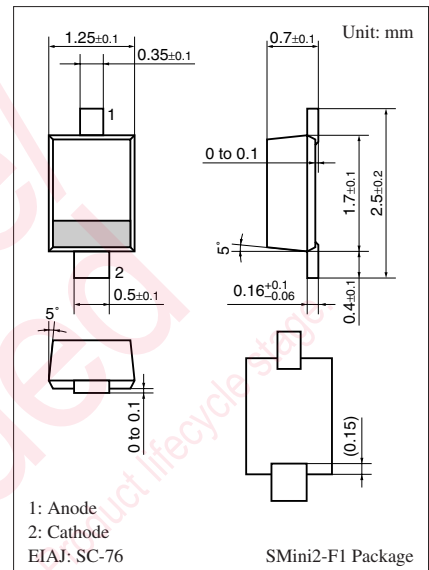
For reduced voltage and temperature compensation

■ Features

- S-mini type package, allowing high-density mounting
- Extremely small reverse current I_R
- Large power dissipation P_D
- Wide forward voltage V_F range

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	6	V
Peak forward current	I_{FM}	150	mA
		100	
Power dissipation	P_D	100	mW
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol

- MA2Z0300A: 3A
- MA2Z0300B: 3B
- MA2Z030WA: 3C
- MA2Z030WB: 3D

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ *1

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	MA2Z030A	V_{F1} $I_F = 1.5 \text{ mA}$	0.56		0.61	V
	MA2Z030B		0.59		0.64	
	MA2Z030WA/WB	$I_F = 10 \mu\text{A}$	0.77			
Forward voltage	MA2Z030WA	V_{F2} $I_F = 3 \text{ mA}$	1.18		1.28	V
	MA2Z030WB		1.26		1.36	
Reverse current	I_R	$V_R = 6 \text{ V}$			1.0	μA
Temperature coefficient of forward voltage *2	MA2Z030A/B	$-\Delta V_F / \Delta T$ $I_F = 1.5 \text{ mA}$		2.0		mV/ $^\circ\text{C}$
	MA2Z030WA/WB			4.6		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

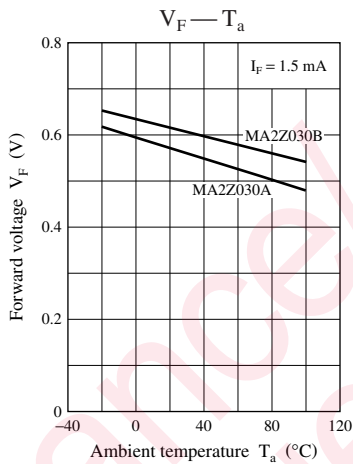
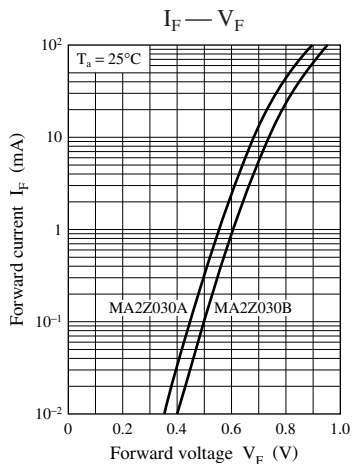
2. Absolute frequency of input and output is 100 MHz.

3. *1: The temperature must be controlled 25°C for V_F measurement. V_F value measured at other temperature must be adjusted to $V_F(25^\circ\text{C})$.

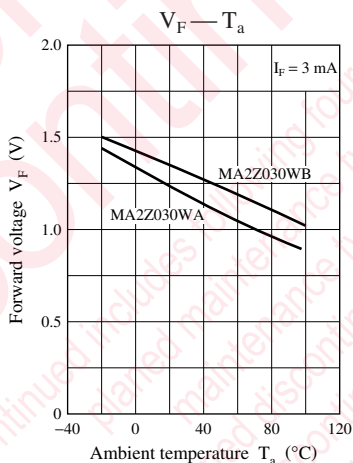
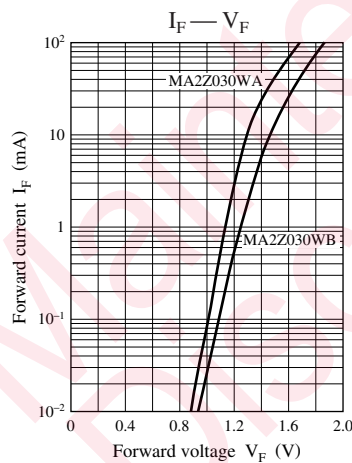
*2: $T_j = 25^\circ\text{C}$ to 125°C

Note) The part numbers in the parenthesis show conventional part number.

Characteristics charts of MA2Z030



Characteristics charts of MA2Z030W



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